

REMARKS

Upon entry of this amendment, claims 1, 4 and 6-28 are all the claims pending in the application. Claims 2, 3 and 5 have been canceled by this amendment, and claims 25-28 have been added as new claims. No new matter has been added. Applicants note that each of claims 25-28 corresponds to the elected invention, and acknowledge that claims 13-24 are drawn to a non-elected invention.

I. Claim Rejections

A. Claims 1, 2, 4, 5 and 7-12 were rejected under 35 U.S.C. § 102(a) as being anticipated by Nogiwa (JP 2003-142897).

Regarding the Nogiwa reference (JP 2003-142897), the Examiner noted in the Office Action that it is unclear whether this reference is by "another" because three of the inventors (Tasuki Nogiwa, Mitsuhiro Ikeda and Mineo Tokunaga) of the reference are in common with the inventors of the present application, and that a fourth inventor of the reference (Masaru Yamauchi) has the same last name as the fourth inventor (Hiroshi Yamauchi) of the present application, but a different first name.

Applicants confirm that the difference in first names for the "Yamauchi" inventor in the reference and the present application is due solely to a translational error in the reference, and that the inventorship of the reference and the present application are identical.

Accordingly, as the inventorship in the reference and in the present application are the same, Applicants note that the Nogiwa reference (JP 2003-142897) is not by "another", and therefore does not qualify as prior art against the present application. Accordingly, Applicants kindly request that this rejection be withdrawn.

B. Claims 1-12 were rejected under 35 U.S.C. § 102(b) as being anticipated by Ishikawa (JP 2001-144430); and claim 3 was rejected under 35 U.S.C. 103(a) as being unpatentable over Ishikawa (JP 2001-144430) in view of Shimizu (JP 2002-374062).

Applicants note that claim 3 has been canceled, and that the features recited therein have been substantially incorporated into claim 1. In addition, Applicants note that claim 1 has also been amended so as to further distinguish the claim from the Ishikawa reference and the Shimizu reference.

In particular, Applicants note that claim 1 has been amended to recite that an adhesive region and a non-adhesive region are provided on the first surface of the base member, the non-adhesive region being provided in the adhesive region, wherein the adhesive material is provided in a portion of the adhesive region other than the non-adhesive region, and wherein the base member is provided with through holes penetrating through the non-adhesive region from the first surface of the base member to the second surface of the base member.

Applicants respectfully submit that the Ishikawa reference and the Shimizu reference do not teach or suggest such a combination of features.

Regarding the Ishikawa reference, Applicants note that this reference discloses a jig having a base fixture 1 and an adhesive layer 2 provided in a Zagury section 10 (see paragraph [0009]). As explained in Ishikawa, the adhesive layer 2 is used to adhere to a printed wiring board 4 (see Abstract and Fig. 1).

Thus, in Ishikawa, while an adhesive layer 2 for adhering to a printed wiring board 4 is provided on a fixture base 1, Applicants respectfully submit that Ishikawa does not disclose or suggest at least the above-noted features recited in amended claim 1 of the non-

adhesive region being provided in the adhesive region, wherein the adhesive material is provided in a portion of the adhesive region other than the non-adhesive region, and wherein the base member is provided with through holes penetrating through the non-adhesive region from the first surface of the base member to the second surface of the base member.

Regarding the Shimizu reference, Applicants note that this reference discloses a conveyance pallet 104 which is thinly coated with an adhesive 16, wherein a circuit board 10 is aligned with and pasted onto the conveyance pallet 104 by using pins 114 of a positioning jig 112 (see Fig. 1 and Abstract). In particular, as shown in Fig. 1 of Shimizu, the pins 114 are able to align with the holes 108 of the conveyance pallet 104 and the holes 18 of the circuit board 10. Further, by coating the conveyance pallet 104 with the adhesive 16, it is explained in Shimizu that the whole backside of the circuit board 10 is bonded to the conveyance pallet 104 (see Fig. 1 and Abstract).

In the Office Action, the Examiner has indicated that the conveyance pallet 104 of Shimizu corresponds to the "base member" as recited in the claimed invention, and that the positioning holes 108 of Shimizu correspond to the "through holes" as recited in the claimed invention.

Based on the foregoing description of Shimizu, however, Applicants respectfully submit that the conveyance pallet 104 of Shimizu is not provided with an adhesive region and a non-adhesive region in the adhesive region. As such, Applicants respectfully submit that Shimizu also does not include through holes that penetrate through a non-adhesive region of the conveyance pallet 104.

Accordingly, Applicants respectfully submit that Shimizu does not disclose or suggest the above-noted features recited in amended claim 1 drawn to an adhesive region and a non-adhesive region being provided on the first surface of the base member, the non-adhesive region being provided in the adhesive region, wherein the adhesive material is provided in a portion of the adhesive region other than the non-adhesive region, and wherein the base member is provided with through holes penetrating through the non-adhesive region from the first surface of the base member to the second surface of the base member.

As explained in an illustrative, non-limiting embodiment of the present invention, by providing through holes in the base member which penetrate through a non-adhesive region, after mounting electronic components, the substrate can be easily removed from the substrate support jig by inserting pins into the through holes from the second surface of the base member or by supplying air into the through holes (e.g., see paragraph [0114]).

In view of the foregoing, Applicants respectfully submit that the combination of Ishikawa and Shimizu does not teach, suggest or otherwise render obvious all of the features recited in amended claim 1. Accordingly, Applicants submit that claim 1 is patentable over the cited prior art, an indication of which is kindly requested. Claims 2, 4, 6-12 and new claims 25-28 depend from claim 1 and are therefore considered patentable at least by virtue of their dependency.

Regarding non-elected claims 13-24, Applicants note that each of independent claims 13, 23 and 24 has been amended so as to include all of the features recited in claim 1. Accordingly, as these claims include all of the features recited in claim 1, upon

allowance of claim 1, Applicants submit that claims 13, 23 and 24 should be rejoined in accordance with MPEP § 821.04 and indicated as allowable.

Claims 14-22 depend from claim 13 and are therefore considered patentable at least by virtue of their dependency.

C. Claim 6 was rejected under 35 U.S.C. § 103(a) as being unpatentable over Ishikawa (JP 2001-144430). Claim 6 depends from claim 1. Applicants submit that claim 6 is patentable over Ishikawa for at least the same reasons as discussed above with respect to claim 1.

III. Conclusion

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

Respectfully submitted,

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